g		GE Industri	al Systems	Functional Testing Specification					
	Renewal Ser Louisville, K			LOU-GEF-WMII-					
Test Procedure for: Work Master II w/ Series 6 Interface									
DOCUM	MENT REVISION STATUS	S: Determined by the last e	ntry in the "REV" and	"DATE" column					
REV.		DESCRIPTION		SIGNA					
Α	Initial release			Jeffrey D	D. Barton 10/23/20	002			
В									
С									
© COPY	VDICUT CENEDAL ELECT	EDIC COMPANIV							
© COPYRIGHT GENERAL ELECTRIC COMPANY PROPRIETARY INFORMATION – THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION OF GENERAL ELECTRIC COMPANY AND MAY NOT BE USED OR DISCLOSED TO OTHERS, EXCEPT WITH THE WRITTEN PERMISSION OF GENERAL ELECTRIC COMPANY.									
	RED BY by D. Barton	REVIEWED BY	REVIEWED	BY QU	JALITY APPROVAL Robert Dunll				
DATE	202123/2002	DATE	DATE		ATE 0/24/2002				

TIWM2.doc
REV. A

GE Industrial Systems
Renewal Services
Louisville, KY

Page 2 of 4

Functional test procedure for: Test Procedure.doc

1. SCOPE

1.1 This is a functional testing procedure for a: Test Procedure.doc

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
2.1.1

4. ENGINEERING REQUIREMENTS

- 4.1 Equipment Cleaning
 - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.
- 4.2 Equipment Inspection
 - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
 - 4.2.1.1 Wires broken or cracked
 - 4.2.1.2 Terminal strips / connectors broken or cracked
 - **4.2.1.3** Loose wires
 - 4.2.1.4 Components visually damaged
 - 4.2.1.5 Capacitors leaking
 - 4.2.1.6 Solder joints damaged or cold
 - 4.2.1.7 Circuit board burned or de-laminated
 - 4.2.1.8 Printed wire runs burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description	
1		P70 Configuration Software	
1		"The Troubleshooter" Diag. Software	
1		Series 6 Software and Cable	
1		Series 6 CPU w/ I/O	
1		DVM	

TIWM2.doc	g GE Industrial Systems	Page 3 of 4
REV. A	Renewal Services Louisville, KY	

6. TESTING PROCESS

- 6.1 Setup
 - **6.1.1** Install power cable to UUT.
 - 6.1.2 Connect Series 6 Cable to UUT Series 6 Interface Card and Series 6 CPU.

6.2 Testing Procedure

- 6.2.1 Power up UUT.
- **6.2.2** Verify UUT boots to Hard Drive; DOS prompt. If UUT fails to boot to H/D, run P70 Configuration S/W and follow directions prompted on display.
- **6.2.3** Verify UUT reads Floppy disks.
- **6.2.4** Reboot UUT with "The Troubleshooter" diag. software. Verify all peripherals pass that are needed for the operation of UUT. (i.e. keyboard, processor, hard drive and controller, motherboard, display.)
- 6.2.5 Reboot UUT.
- **6.2.6** Using Series 6 software, (accessed by either hard drive or floppy drive), Verify communication with Series 6 CPU and displaying program from Series 6 CPU.
- 6.2.7 Power off UUT.
- **6.2.8** Remove main rear cover.
- 6.2.9 Remove Series 6 Interface card.
- **6.2.10** Verify CMOS Battery's voltage above +5.7Vdc. (If not It must be replaced.)
- 6.2.11 Install Series 6 Card back into UUT.
- **6.2.12** Power up UUT and verify boot to hard drive; DOS prompt.
- 6.2.13 Reassemble UUT rear cover.
- 6.3 ***TEST COMPLETE ***

7. NOTES:

8. Oscilloscope Verification Examples:

Fig. 1

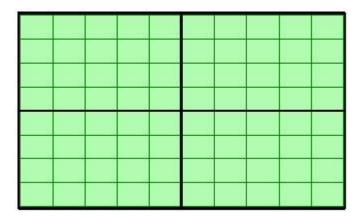


Fig. 2

